

SOT2100-1

WLCSP83, wafer level chip scale package, 83 terminals, 0.4 mm pitch, 4.6 mm x 4.2 mm x 0.75 mm body

7 October 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP83
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	16-09-2020
Manufacturer package code	98ASA01708D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.5	4.6	4.7	mm
package width	4.1	4.2	4.3	mm
package height	-	0.75	0.79	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	83	-	



2 Package outline

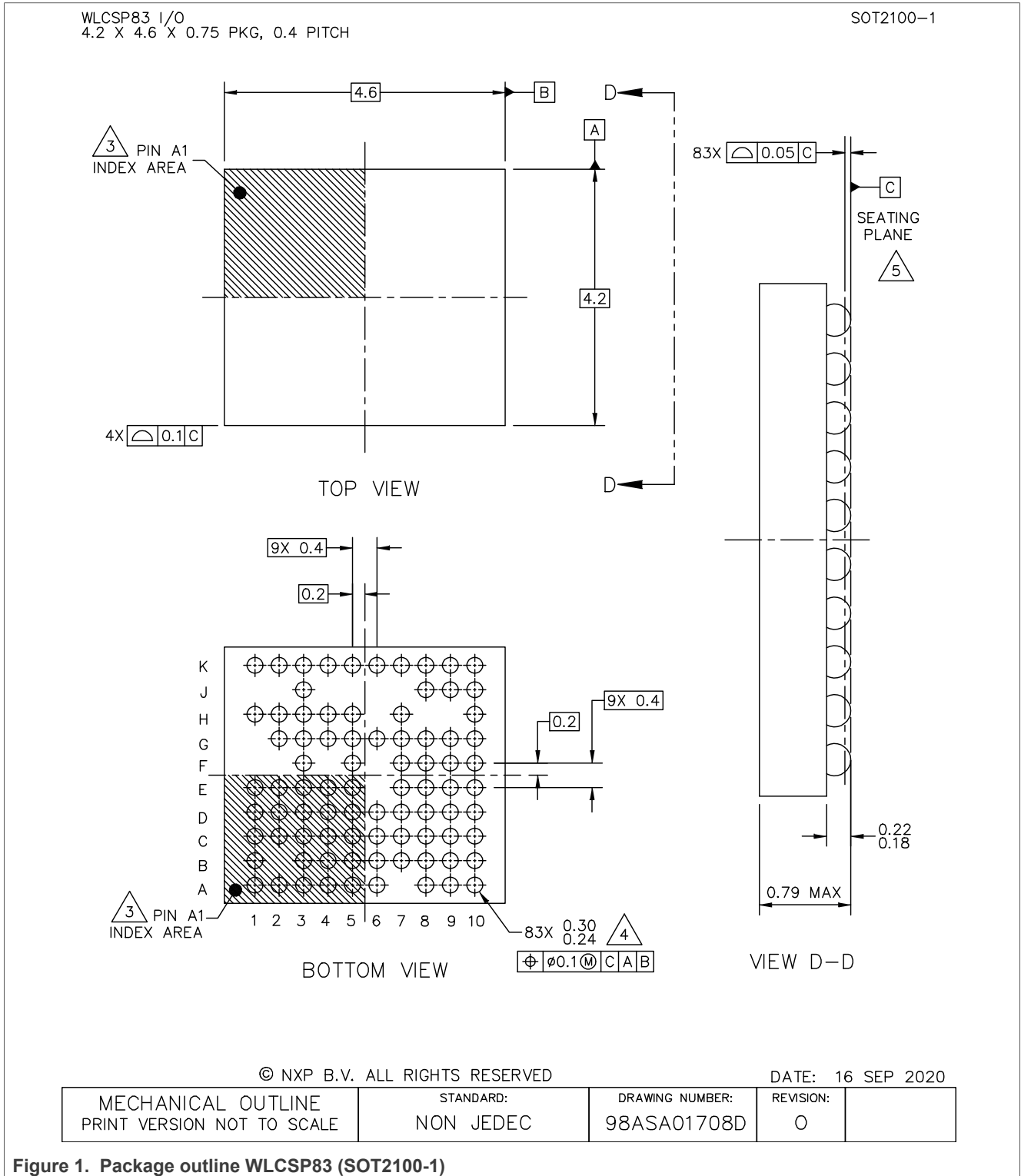
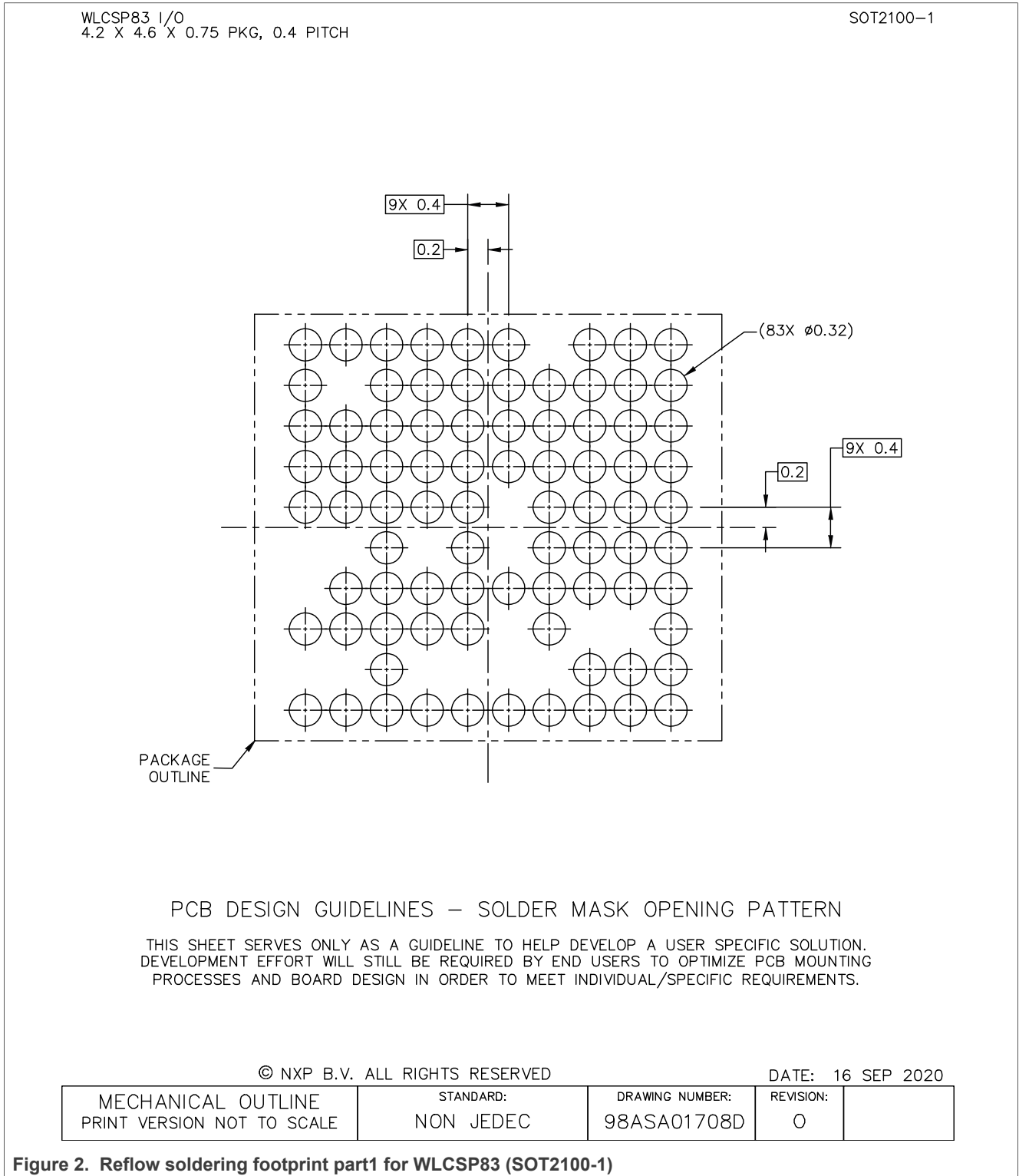


Figure 1. Package outline WLCSP83 (SOT2100-1)

3 Soldering



WLCSP83, wafer level chip scale package, 83 terminals, 0.4 mm pitch, 4.6 mm x 4.2 mm x 0.75 mm body

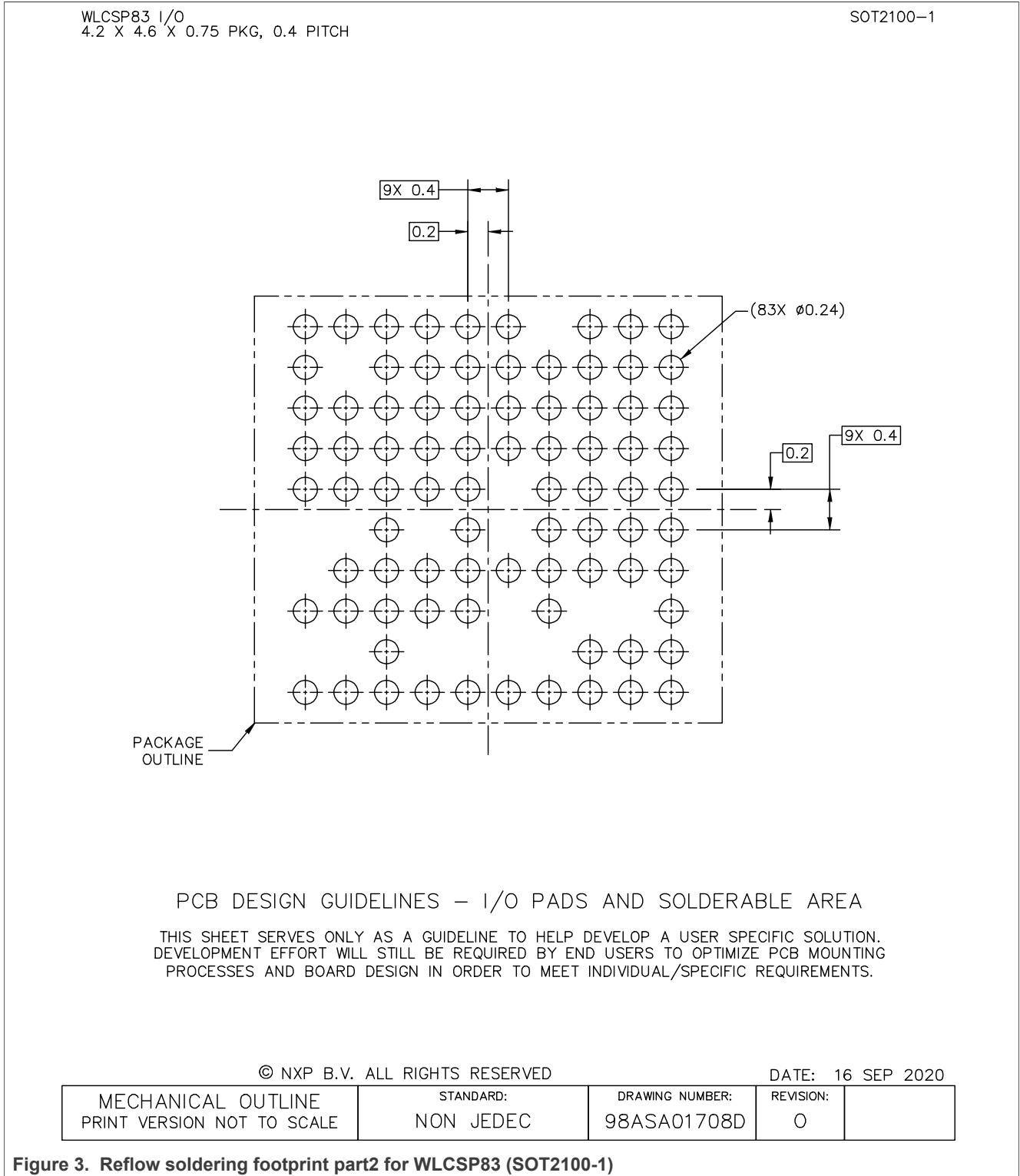


Figure 3. Reflow soldering footprint part2 for WLCSP83 (SOT2100-1)

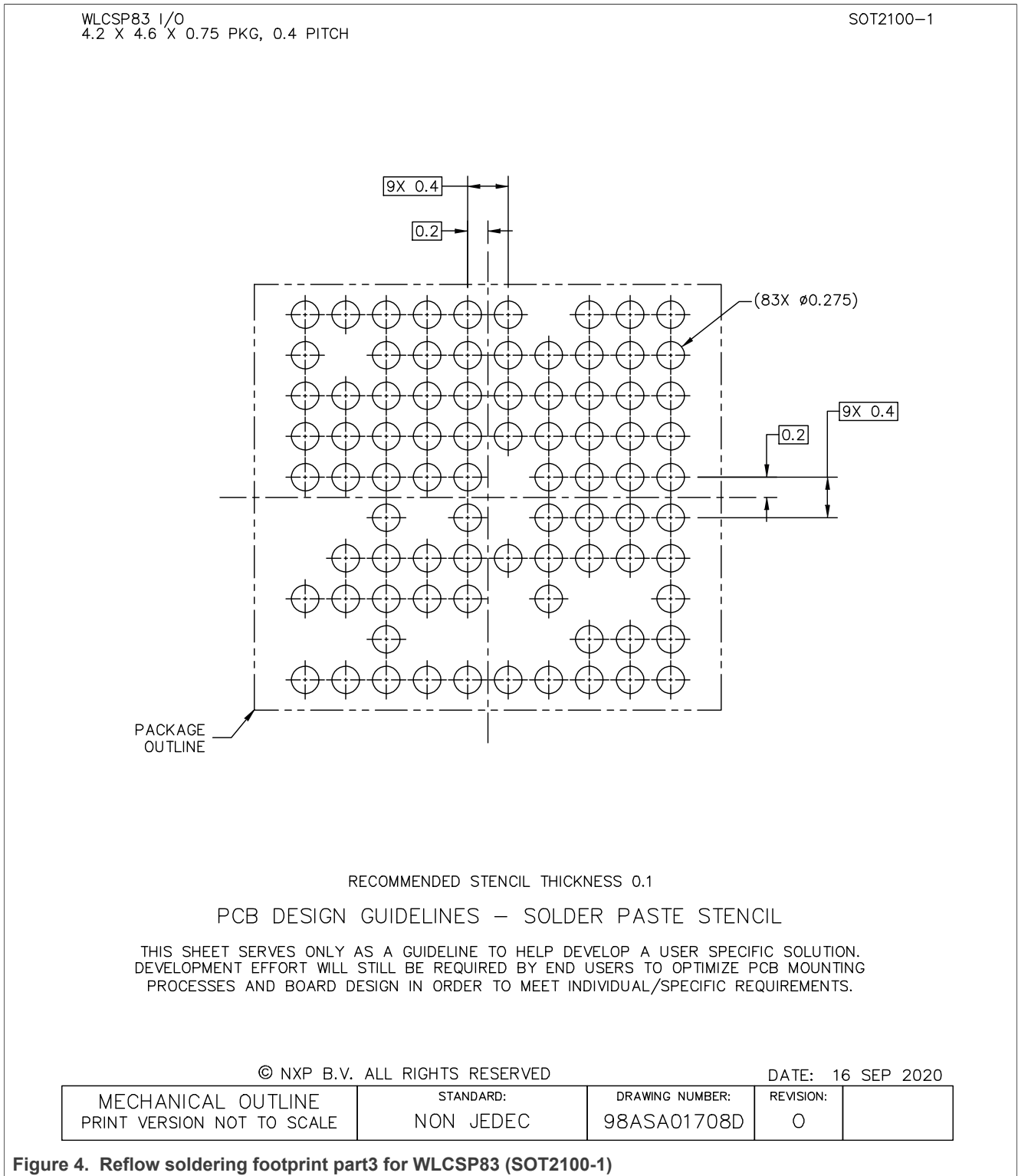
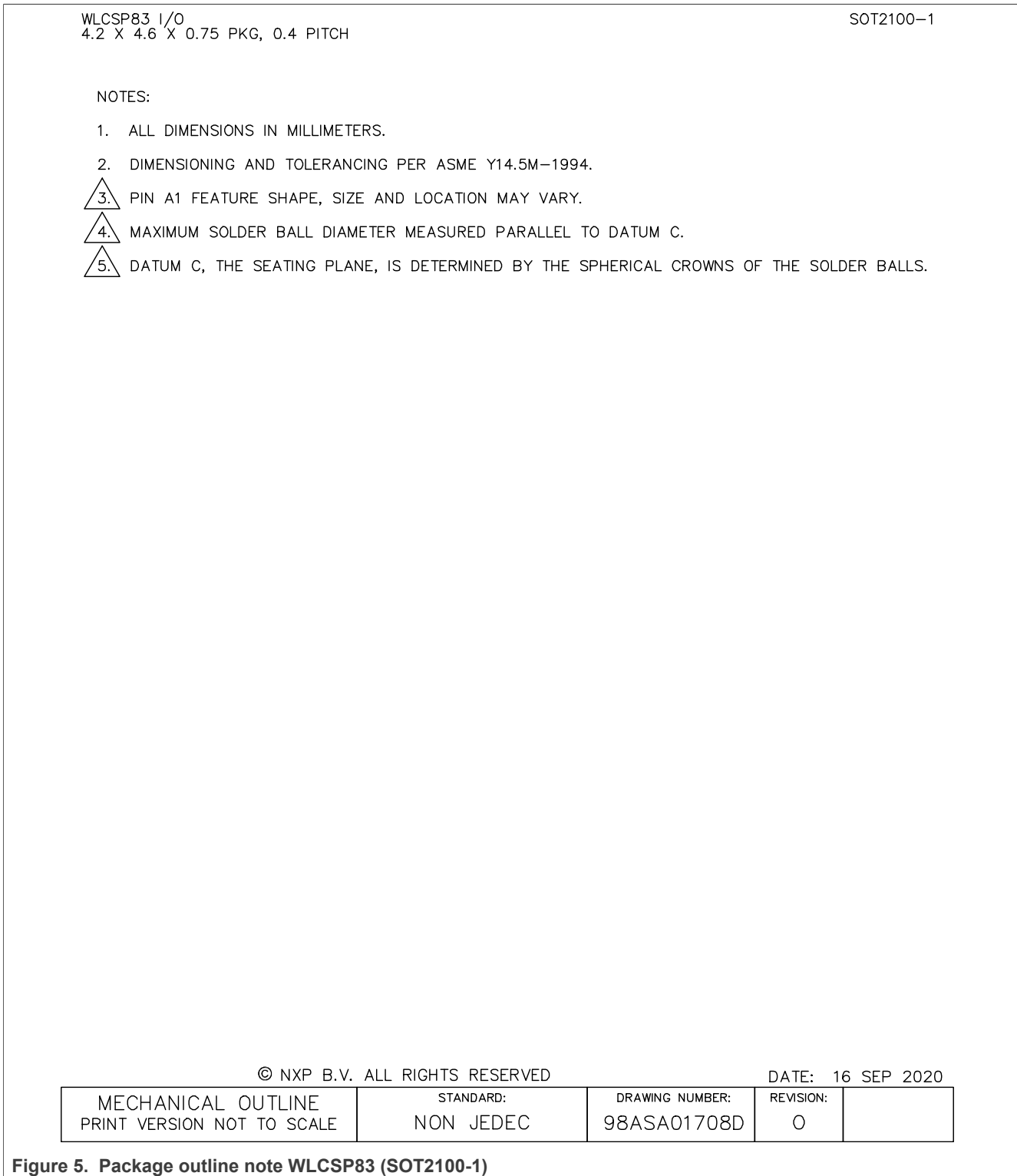


Figure 4. Reflow soldering footprint part3 for WLCSP83 (SOT2100-1)

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4 Legal information

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